SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Shielded SMD Power Inductor	ABC'S DWG NO.	SE1509□□□□L□-□□□		
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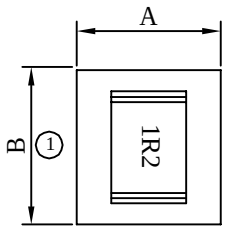
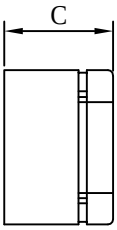
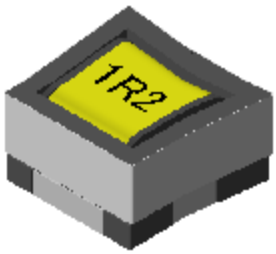
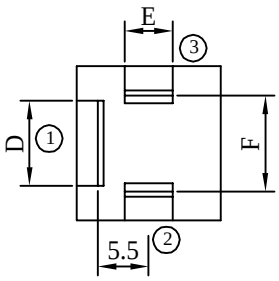
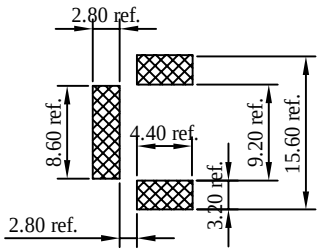
Ⅰ．Configuration and dimensions：











（PCB Pattern）

Unit：m/m

A	B	C	D	E	F
15.0±0.40	15.0±0.40	9.50±0.50	7.80±0.50	4.00±0.25	10.00 ref.

Ⅱ．Schematic diagram：

Ⅲ．Description：

a．Ferrite ER core construction.

b．Magnetically shielded.

c．Enamelled copper wire：F class

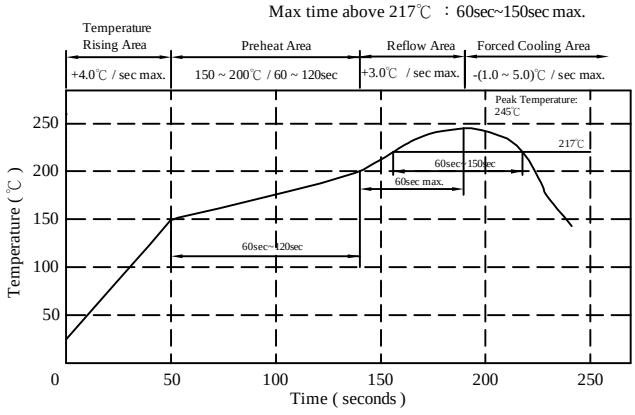
d．Product weight： 7.35g（ref.）

e．Moisture sensitivity Level 1

f．Products comply with RoHS' requirements

g．Halogen free available

Peak Temp：245℃ max.
Max. Peak Temp - 5℃ ：30sec max.
Max time above 217℃ ：60sec~150sec max.



Ⅳ．General specification：

a・Storage temp. : -40℃~ +125℃

b・Operating temp. : -40℃ ~ +125℃

(Temp. rise included)

c．Resistance to solder heat ：245℃,10 sec.

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Ⅴ．Electrical characteristics：

DWG. No.	Inductance (uH)	RDC (mΩ) max.	Irms (A) (△T=40℃ max.) max.	Isat (A) (△L/L0A=20%) typ.
SE15091R2ML□-□□□	1.20±20%	2.0	16.0	19.0
SE15091R4ML□-□□□	1.40±20%	2.0	15.0	18.0
SE15091R8ML□-□□□	1.80±20%	3.0	14.0	18.0
SE15092R0ML□-□□□	2.00±20%	3.0	13.0	16.0
SE15092R5ML□-□□□	2.50±20%	3.4	12.0	14.5
SE15092R8ML□-□□□	2.80±20%	3.4	12.0	14.0
SE15093R0ML□-□□□	3.00±20%	4.3	10.0	13.0
SE15093R6ML□-□□□	3.60±20%	4.3	10.0	12.0
SE15093R9ML□-□□□	3.90±20%	6.5	9.0	11.5
SE15094R5ML□-□□□	4.50±20%	6.5	8.0	10.5
SE15094R8ML□-□□□	4.80±20%	7.2	7.0	10.0
SE15095R6ML□-□□□	5.60±20%	7.2	6.0	9.0

1). □: Packaging information：□Code

2). "-□□□"：Reference code

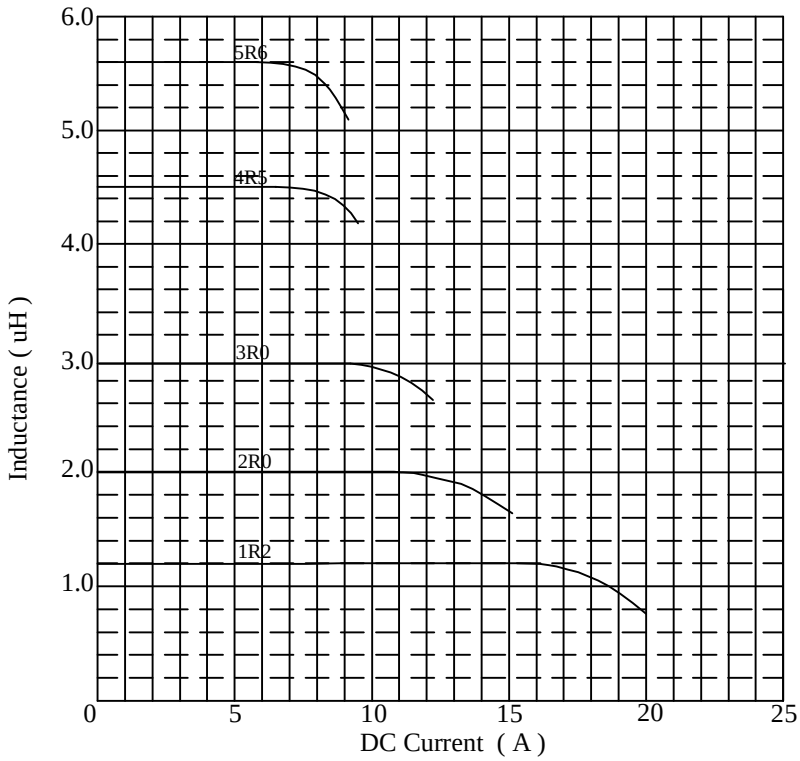
3). Electrical specifications at 25℃

4). Irms base on temp. rise at 40℃ max.& inductance drop 10% max.

5). Inductance Test Freq.：100KHz / 1V

6). Isat base on △L/L0A=20% typ.

@ Inductance VS. DC Superposition Characteristics



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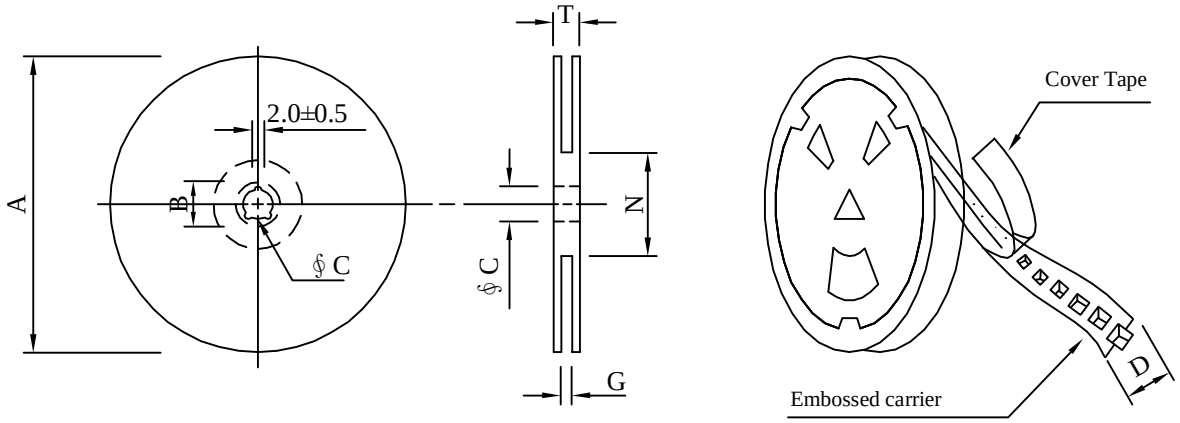
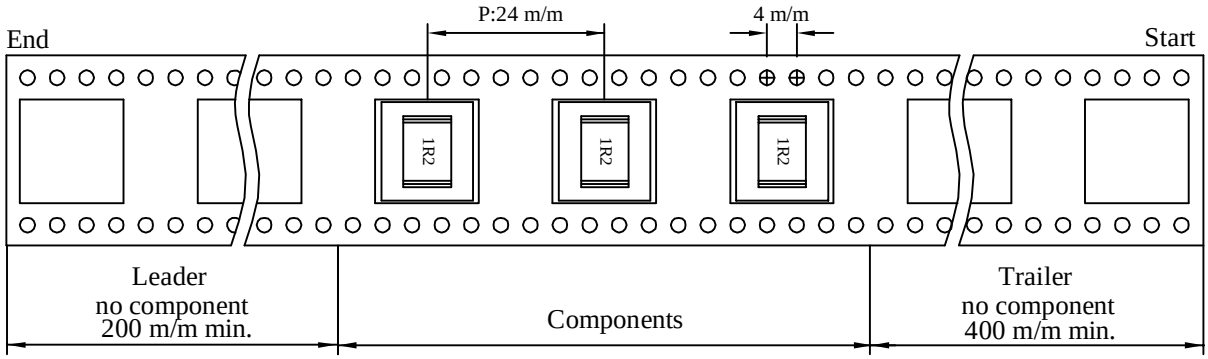
Ⅵ．Packaging information：

(1) Configuration



※Carrier tape width : D



User direction of feed

(2) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
13 - 32	330	21±0.8	13	32	34^{+0}	100^{-0}	38.4

(3) Q'TY & G.W. Per package

Code	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (gw)	Style	Q'TY (pcs)	G.W. (Kg)	Size (cm)
B	200	1370	13 - 32	800	6.8	38 x 37 x 22

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Ⅶ．Reliability test：

Item	Reference documents	Test Condition	Test Specification
1.High Temperature Exposure	MIL-STD-202 Method 108	1.Temperature: 125℃ 2.Time:96 hours.	1.No mechanical and electrical damage. 2.Inductance shall not change more than ±25%.
2.Temperature Cycling	JESD22 Method JA-104	1.Temperature: -40℃ ~ 125℃ 2.Number of cycle:96 cycle 3.Dwell time:30 minutes	1.No mechanical and electrical damage. 2.Inductance shall not change more than ±25%.
3.Biased Humidity Test	MIL-STD-202 Method 103	1.Temperature: 85±5 ℃ 2.Time:96 Hours 3.Humidity: 85±5% RH.	1.No mechanical and electrical damage. 2.Inductance shall not change more than ±25%.
4.Operational Life	MIL-PRF-27	1.Temperature: 125℃ 2.Time:96 hours. 3.Apply rated current.	1.No mechanical and electrical damage. 2.Inductance shall not change more than ±25%.
5.Exeternal Visual	MIL-STD-883 Method 2009	Inspect product constructions, marking and workmanship.	1.No pollution on the surface of products. 2.Clear marking. 3.No crack.
6.Physical Dimensions	JESD22 Method JB-100	Verify physical dimensions to the applicable product detail specification.	Per product specification standard
7.Resistance to solvents	MIL-STD-202 Method 215	Immerse into solvent for 3±0.5 minutes & brush 10 times for therr cycles.	1.No body change in apperarance. 2.No marking blurred. 3.Inductance shall not change more than ±25%.
8.Vibration Test	MIL-STD-202 Method 204	1.Frequency and Amplitued : 10-2000-10 Hz, 1.5 mm. 2.Direction:X, Y, Z 3.Test duration:2 hours for each direction, 6 hours in total.	1.No mechanical and electrical damage. 2.Inductance shall not change more than ±25%.
9.Resistance To Soldering Heat Test	MIL-STD-202 Method 210	1.Highest temperature：245±5℃ 2.Time（temp.≧ 217℃）：60~150 Second. 3.IR reflow times：3 times.	1.No mechanical and electrical damage. 2.Inductance shall not change more than ±25%.
10.Rated current	MIL-STD-202 Method 330	Apply rated current for 5 second.	1.No mechanical and electrical damage. 2.Inductance shall not change more than ±25%.
11.Temperature rise	MIL-PRF-27	Apply rated current for 10 minutes.	1.No mechanical and electrical damage. 2.Inductance shall not change more than ±25%.
12.Over load	MIL-PRF-27	Apply twice as rated current for 5 minutes. (It's not application to some special design)	1.No mechanical and electrical damage. 2.Inductance shall not change more than ±25%.
13.Solderability Test	J-STD-002	1.Baking in pre-testing：155±5℃ / 16Hours±30 min. 2.Peak temperature：240±5℃ 3.Time（temp.≧217℃）：60~150 second. 4.IR reflow times：1 times.	The terminal shall be at least 95% covered with fresh solder.
14.Electrical Characteriazation	User Spec.	1.Operating temperature： -40℃~125℃ 2.Room temperature：25℃.	1.No mechanical and electrical damage. 2.Inductance shall not change more than ±25%.
15.Withstanding Voltage Test	MIL-STD-202 Method 201	1.DV:500V 2.Time:1minutes	1.During the test no breakdown. 2.The characteristic is normal after test.
16.Drop	JESD22-B111	Packaged & Drop down from 1m.In 1 angle 1ridges & 2 surfaces orientation.	1.No case deformation or change in appearance. 2.Inductance shall not change more than ±25%.
17.Terminal Strength Test	JIS-C-6429	1.Apply push force to samples mounted on PCB. 2.Force of 1.8 kg for 60±1 seconds.	After test, inductors shall be no mechanical damage.